



Applied Materials Launches 300mm CMP Product Line; Reflexion System Provides Enabling Factory Efficient Solutions for Five Major CMP Applications

July 10, 2000

SANTA CLARA, Calif.--(BUSINESS WIRE)--July 10, 2000--Applied Materials, Inc. today announced its complete line of factory efficient 300mm CMP (chemical mechanical polishing) solutions with its new Reflexion(TM) system. Covering five major process applications, including copper and low (κ) dielectrics, the Reflexion platform provides the performance and productivity needed for the most advanced chip technologies. Based on Applied Materials' industry-leading Mirra Mesa(TM) architecture, the Reflexion system combines production-proven CMP and cleaning technology with critical innovations in automation and advanced process control to optimize fab efficiency.

"The Reflexion system offers advanced, high productivity processes for all CMP applications, including dielectric, copper, polysilicon and tungsten films, as well as shallow trench isolation (STI), and incorporates many new features that boost wafer output while increasing system availability and wafer yield," said Chris Smith, vice president and general manager of Applied Materials' CMP Product Group. "This new product line accelerates CMP technology with a number of integrated process monitoring and control capabilities, such as particle monitoring, film metrology and the industry's most advanced wafer endpoint detection technology."

The Reflexion system integrates several key capabilities to maximize technical results, space efficiency and productivity. Integrated Mesa cleaning technology provides a two-stage brush scrub with single-wafer megasonics for low defect performance and high wafer output per square foot. Within its fully automated factory interface (FI) module, the Reflexion platform offers a variety of advanced process control (APC) options that virtually eliminate the need for costly test wafers and provide greater overall equipment efficiency. A film thickness metrology unit measures each wafer before and after polishing for precise process results. Applied Materials' Integrated Particle Monitor(TM) (IPM) can also be incorporated to monitor particle levels on blanket and patterned wafers.

Additional features of the Reflexion product include its Titan Head(TM) polishing technology that can tune the film removal rate to match specific wafer characteristics with slurry chemistries, providing superior control over dishing and erosion. The system's FullScan(TM) endpoint technology enables users to scan the entire wafer to precisely control overpolishing, contributing to higher yields and excellent results on copper-based chips.

Applied Materials (Nasdaq:AMAT) is a leader of the Information Age and the world's largest supplier of products and services to the global semiconductor and flat panel display industries. Applied Materials' web site is <http://www.appliedmaterials.com>.

CONTACT: Applied Materials, Santa Clara

Betty Newboe, 408/563-0647 (editorial/media)

Carolyn Schwartz, 408/748-5227 (financial community)